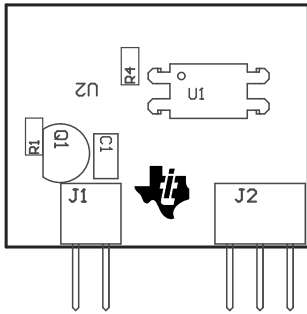


ZZ1 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

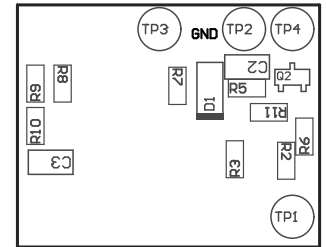
ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: PMP6023-2 | REV: E2 | SUN REV: Not In VersionControl |
| IGNORE -> Top Overlay | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 8/14/2014 2:04:08 PM | TEXAS INSTRUMENTS | |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

| | | | |
|-------------------------------------|----------------------------------|---------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: PMP6023-2 | REV: E2 | SUN REV: Not In VersionControl |
| | IGNORE -> Bottom Overlay | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 8/14/2014 2:04:09 PM | | TEXAS INSTRUMENTS |

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